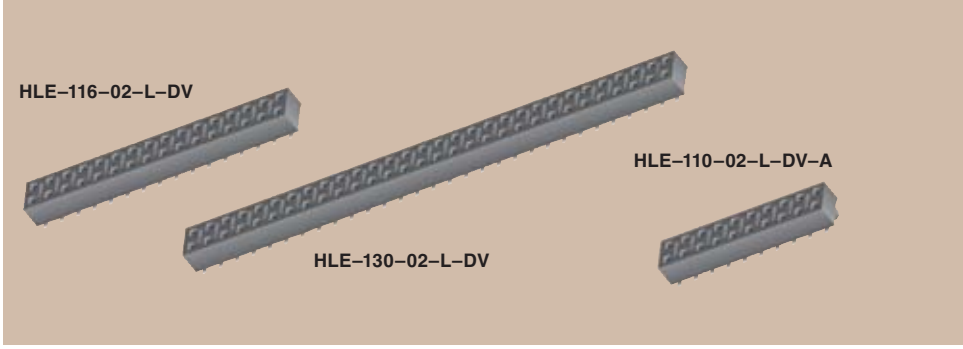
samtec



(2,54mm) .100"

HLE SERIES

COST-EFFECTIVE RELIABLE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HLE

Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
BeCu
Plating:
Au or Sn over 50µ" (1,27µm) Ni
Current Rating:
2.5A @ 80°C ambient
Voltage Rating:
400 VAC
Operating Temp Range:
-55°C to +125°C
Insertion Depth:
(1,78mm) .070" to (3,43mm) .135", pass-through, or (2,59mm) .102" min for bottom entry
Insertion Force:
(Single contact only) 2oz (0,56N) avg.
Withdrawal Force:
(Single contact only) 1.6oz (0,44N) avg.
RoHS Compliant:
Yes

FILE NO. E111594

Processing:

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0,10mm) .004" max (02-20)
(0,15mm) .006" max (21-50)

Note: Some lengths, styles and options are non-standard, non-returnable.

HLE – 1 (NO. PINS PER ROW) – 02 – (PLATING OPTION) – DV – (TAIL OPTION) – (OTHER OPTION)

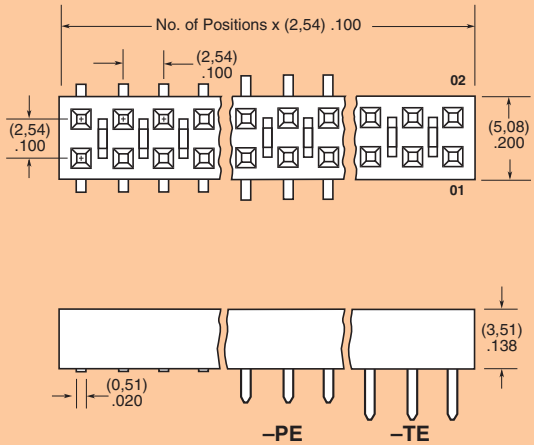
Mates With:
TSW, MTSW, DW, EW, ZW, TLW, TSM, MTLW, HW

–F
= Gold flash on contact, Matte Tin on tail

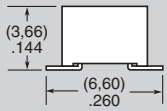
–L
= 10µ" (0,25µm) Gold on contact, Matte Tin on tail

Note: Other Gold plating options available. Contact Samtec.

02 thru 50

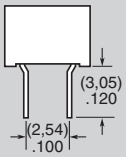


Leave blank for Surface Mount

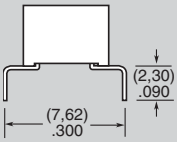


(Requires –BE for Bottom Entry)

–TE
= Through-Hole Top Entry



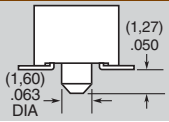
–PE
= Through-hole Pass-Through Entry



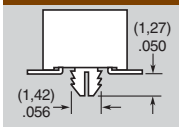
(Requires –BE for Bottom Entry)

–BE
= Bottom Entry (N/A with –TE)

–A
= Alignment Pin (4 positions min.) Metal or plastic at Samtec discretion (N/A with -TE, -PE & -LC)

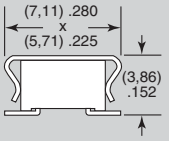


–LC
= Locking Clip (2 positions min.) (N/A with -A) (Manual placement required)



–K
= (6,50mm) .256" DIA Polyimide Film Pick & Place Pad (3 positions min.) Not available with –TE or –PE tail option

–P
= Metal Pick & Place Pad (3 positions min.)



–TR
= Tape & Reel Packaging (29 positions max.)

Due to technical progress, all designs, specifications and components are subject to change without notice.